AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (previously presented) A compression-bond-connection substrate to be connected by compression-bonding to a compression-bonding target object having opposing-side terminals, comprising a compression-bonding-side surface to be connected to the compression-bonding target object, substrate-side terminals to be conductively connected to the opposing-side terminals, and backside wiring patterns formed on a reverse face of the compression-bonding-side surface, characterized in that step compensation patterns having substantially the same thickness as that of the backside wiring patterns are formed on the reverse face in positions corresponding to the backsides of the substrate-side terminals.

2. (original) A compression-bond-connection substrate as stated in claim 1, characterized in that at least some of the step compensation patterns are formed on the reverse face in positions corresponding to the backsides of regions overlapping with a plurality of the substrate-side terminals.

3. (original) A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is an IC chip, and the opposing-side terminals are bumps to be formed on an active face of the IC chip.

4. (previously presented) A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is a substrate of a liquid crystal panel comprising a pair of substrates opposing each other and a liquid crystal sealed between the substrates, and the opposing-side terminals are external-connecting terminals formed on at least one of the substrates.

5. (previously presented) A compression-bond-connection substrate as stated in Claim 1 characterized so as to be conductively connected to the compression-bonding target object via an anisotropic conductive adhesive.

6. (previously presented) A compression-bond-connection substrate as stated in claim 1, characterized in that the compression-bonding target object is a liquid crystal device including a pair of substrates opposing each other and a liquid crystal sealed between the substrates.

7. (original) An electronic equipment comprising a liquid crystal device, characterized in that the liquid crystal device is as stated in claim 6.

8. (currently amended) A liquid crystal device comprising:

a substrate having first and second sides;

a liquid crystal panel opposed to the first side of the substrate;

a plurality of external-connecting terminals formed on the liquid crystal panel;

a plurality of substrate-side terminals formed on the first side of the substrate and opposed to the external-connecting terminals;

an adhesive material disposed between the substrate and the liquid crystal panel;

a plurality of wirings formed on the second side of the substrate; and

a compensation member formed on the second side of the substrate;

wherein the compensation member has substantially the same thickness as the wirings.

9. (cancelled).

10. (previously presented) The liquid crystal device of Claim 8, characterized in that said target object is an IC chip.

11. (previously presented) The liquid crystal device of Claim 8, characterized in that said target object is a substrate of a liquid crystal panel.

12. (currently amended) The liquid crystal device of Claim 8, characterized in that said adhesive material is an ~~anistropic~~ anisotropic conductive adhesive.

13. (previously presented) A connection assembly comprising:

a substrate having first and second sides;

a target object opposed to the first side of the substrate;;

a plurality of target object-side terminals formed on the target object;

a plurality of substrate side terminals formed on the first side of the substrate, and opposed to the target object-side terminals;

an adhesive material disposed between the substrate and the target object;

a plurality of wirings formed on the second side of said substrate; and

a compensation member formed on the second side of the substrate, the compensation member having substantially the same thickness as the wirings.

14. (previously presented) A connection assembly comprising:

a substrate having first and second sides;

an IC chip opposed to the first side of the substrate;

a plurality of bumps formed on the IC chip;

a plurality of lands formed on the first side of the substrate, and opposed to the bumps;

an adhesive material disposed between the substrate and the IC chip;

a plurality of wirings formed on the second side of the substrate; and

a compensation member formed on the second side of the substrate, the compensation member having substantially the same thickness as the wirings.